

DESCRIPTION:

The products are 4-pin optical relays. The device is a very small outline non-leaded photorelay suitable for surface-mount assembly. It consists of an infrared LED optically coupled to a photo-MOSFET and is housed in a S-VSON4 package. It features low output capacitance, COFF, and thus fast on/off switching of a high-frequency signal, making it ideal for switching applications in high-speed testers. The products are widely used in automatic test equipment, high-speed logic IC testers, high-speed memory testers and measuring instruments.

MAIN FEATURES

Isolation voltage 500 Vrms

Operating temperature range -40°C to 110°C

REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

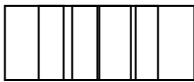
CQC approved

VDE approved

UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

E Î



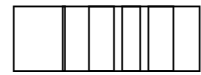
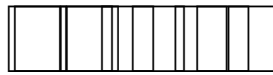
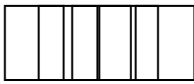
Soldering Temperature	T_{sol}	260	°C
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NOTE1: 100 μ s pulse, 100Hz frequency

NOTE2: AC for 1 minute, R.H.=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Input	Forward Voltage	V_F	$I_F=10mA$	-	2	2.5	V
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA
	Input Capacitance	C_{in}	$V=0V$ $f=1MHz$	-	30	-	pF
Detector	Off-state Current	I_{OFF}	$V_{OFF}=100V$	-	1	10	nA
	Output Capacitance	C_{OFF}	$V=0V$ $f=1MHz$ $t<1s$	-	70	100	pF
Coupled	Trigger LED Current	I_{FT}	$I_{ON}=1A$	-	0.6	1	mA
	Return LED Current	I_{FC}	$I_{OFF}=10\mu A$	0.1	-	-	mA
	On-state Resistance	R_{ON}	$I_{ON}=1A$ $I_F=5mA$ $t<1s$	-	0.3	0.5	Ω
Switching Characteristics	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	-	10	0	Q



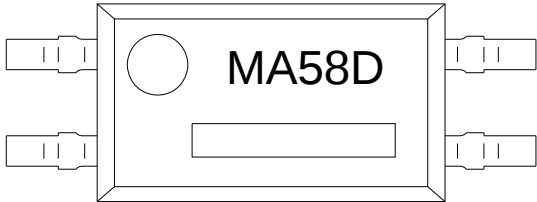
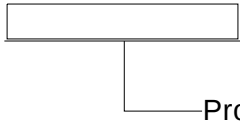
ORDERING INFORMATION

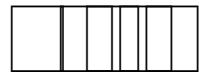
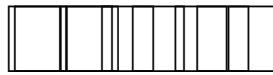
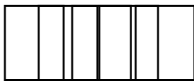
J	OC	M	A	5	8	D	-SVS4	/
JieJie Microelectronics Co., Ltd.	Opto Coupler	MOS	A:1NO	5:V _{OFF} :100V	8:I _{ON} :1A		S-VSON4	None:T1 R:T2
						I _{FT} ≤1mA		

Packing Quantity

Option	Quantity
S-VSON4	2500 Units/Reel

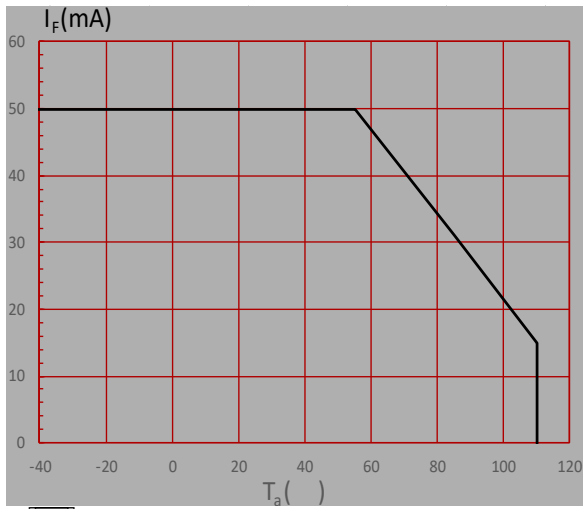
MARKING

	 Production Information Code
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Characteristics Curves

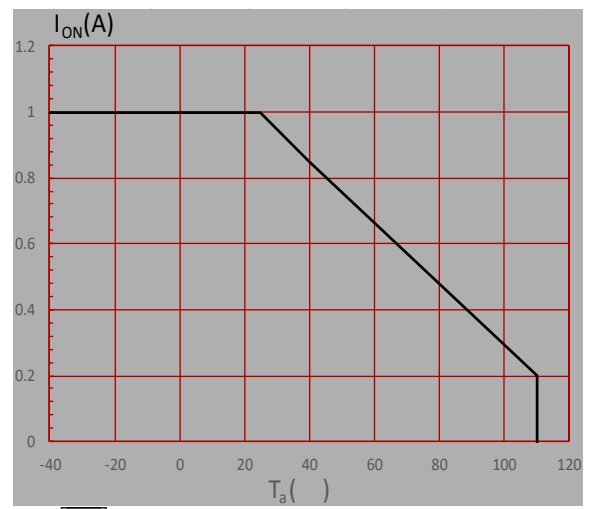
 Max. Allowable LED Forward Current vs. Ambient Temperature



 LED Forward Current vs. LED Dropout Voltage



 On-state Current vs. Ambient Temperature

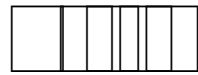
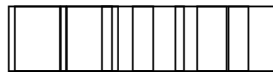
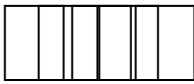


 On-state Current vs. On-state Voltage

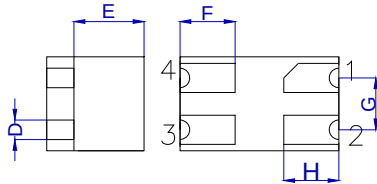
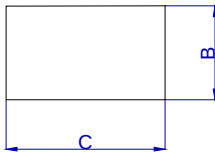
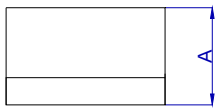
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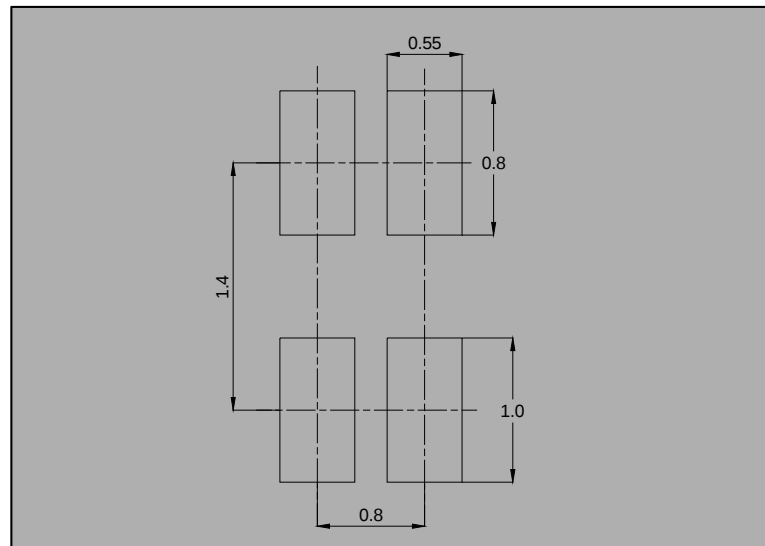


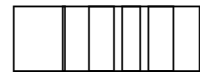
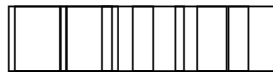
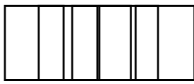
Package Dimension (Unit: mm)



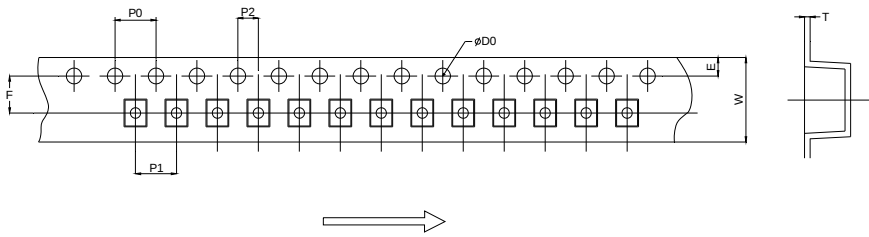
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.30		1.70	0.051		0.067
B	1.65		2.05	0.065		0.081
C	2.05		2.45	0.081		0.096
D	0.10		0.50	0.004		0.020
E	0.88		1.28	0.035		0.050
F	0.775		1.175	0.031		0.046
G	0.60		1.00	0.024		0.039
H	0.575		0.975	0.023		0.038

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

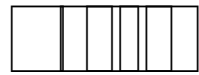
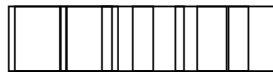
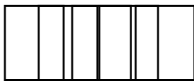




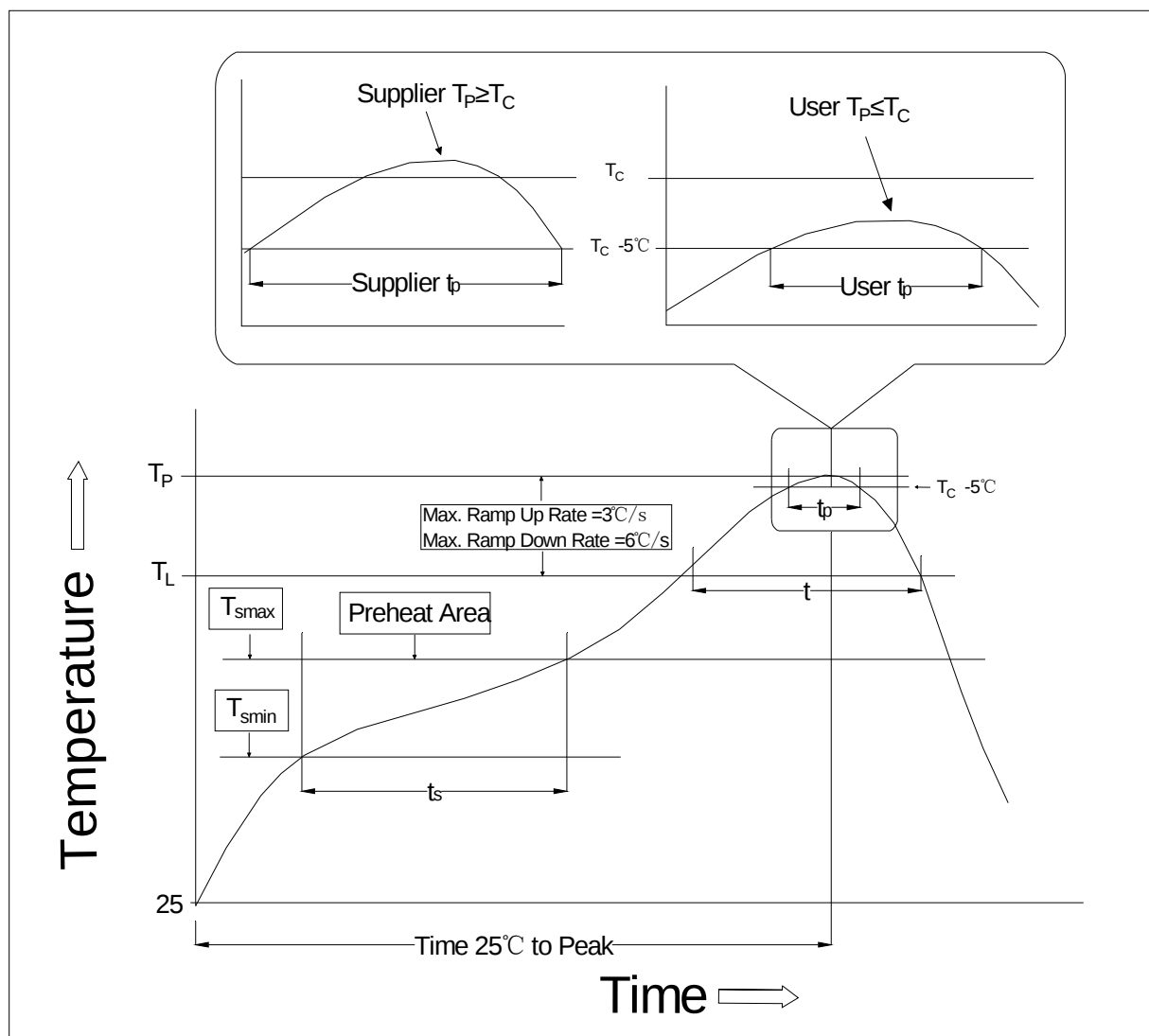
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



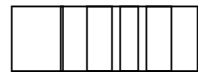
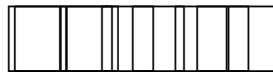
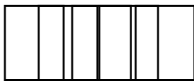
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	3.90	4.00	4.10	0.154	0.157	0.161
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	3.40	3.50	3.60	0.134	0.138	0.142
T	0.20	0.25	0.30	0.008	0.010	0.012
W	7.70	8.00	8.30	0.303	0.315	0.327



REFLOW INFORMATION



Temperature Min. (Tsmin)	100°C	150°C
Temperature Max. (Tsmax)	150°C	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidus Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (tP) within 5°C of 260°C	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6°C/second	3-6°C/second
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 3

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